

European Wireless Conference 2022

Welcome

Dear Friends and Colleagues,

European Wireless (EW) is a key venue for European and worldwide researchers to be acquainted with the latest trends in wireless communications and networking. The main theme of EW 2022 is "6G and 5G beyond Communications". This 27th edition of EW (EW 2022) will be held in Dresden, Germany, September 19-21, 2022. Currently, the conference is planned to be in presence, hosting authors' presentations, and allowing for interactions and networking among the participants. Nevertheless, if health and traveling rules and restrictions arise, the hybrid mode will also be considered and set up.

Keeping on the tradition of the previous European Wireless editions, the scope of EW2022 is broad, including, in addition to the subjects of the main conference theme, the most relevant topics in 6G and 5G and beyond communications. The Organizing Committee of EW2022 has prepared a stimulating program including technical presentations, tutorials, invited talks by distinguished keynote speakers.

EW2022 offers one tutorial entitled "Beyond Massive MIMO in 6G communication networks: Cell-Free massive MIMO and Reconfigurable Intelligent surfaces.", given by Giovanni Interdonato and Carmen D'Andrea.

We would like to thank all of our colleagues who have been contributing to make EW2021 a great event, and specifically the Technical Program Co-Chairs (Falko Dressler and Chan-Byoung Chae), the Special Session Chairs (Slawomir Stanczak, Florian Kaltenberger, Meryem Simsek, Oliver Holland, Holger Boche, Christian Deppe, Juan Cabrera, Riccardo Bassoli, Janis Nötzel, Wolfgang Kellerer, Hans Dieter Schotten, Vincenzo Sciancalepore, Bin Han, Christoph Lipps, Norman Franchi, Rastin Pries), the Tutorials Chair (Fabrizio Granelli), the Publication Chair (Leonardo Badia), the Program Chair (Riccardo Bassoli), and the Local Organization Chair (Rico Radeke).

We hope that you can profitably exploit the chance to meet the scholars and researchers coming from all around the world to attend EW2022. EW2022 actually intends to offer a friendly atmosphere to establish new personal contacts and encourage exchange of ideas with focus on 6G 5G and beyond communication technologies.

Once more, on behalf of the whole Organizing Committee of European Wireless 2022, we are pleased to welcome you, hoping that you have a truly inspiring and rewarding experience. We will do our very best to make your staying in Dresden comfortable and enjoyable!

Frank H.P. Fitzek

European Wireless 2022, General Chair

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